

WHAT IS CLAIMED IS:

1. An image sensor package to be electrically connected to a printed circuit board, the image sensor comprising:

5 a plurality of lower metal sheets arranged in an array, each of the lower metal sheets having an upper surface and a lower surface, and a first hole ;

a plurality of upper metal sheets arranged in an array, each of the upper metal sheets having an upper surface and a lower surface, and a second hole penetrated from the upper surface to the lower surface , and the second hole being corresponded with the first hole of the lower metal sheets , the lower surface of
10 the upper metal sheets being stacked on the lower metal;

an encapsulant for encapsulating the lower metal sheets and the upper metal sheets, and the encapsulant filled into the first hole and second hole to tighten the upper metal sheets and the lower metal sheets, wherein the upper surfaces of the lower metal sheets are exposed from the encapsulant, the lower surfaces of the
15 lower metal sheets are exposed from the encapsulant and electrically connected to the printed circuit board, and the encapsulant is formed with a frame layer around the upper surfaces of the upper metal sheets to define a chamber together with the upper metal sheets;

a photosensitive chip being arranged within the chamber;

20 a plurality of wires for electrically connecting the photosensitive chip to the upper surfaces of the lower metal sheets;

a transparent layer arranged on the frame layer of the encapsulant to cover the photosensitive chip.

2. The image sensor package according to claim 1, wherein the encapsulant is made of industrial plastic material, and the encapsulant and the frame layer are
5 integrally formed.

3. The image sensor package according to claim 1, wherein the transparent layer is a piece of transparent glass.

4. The image sensor package according to claim 1, wherein the first hole of the lower metal is a cavity.

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